EOS/ESD Association, Inc. is sponsoring the 3rd International EOS/ESD Symposium on Design and System (IEDS). IEDS 2024 is dedicated to the fundamental understanding of issues related to electrostatic discharge on design and system and the application of this knowledge to the solution of problems. The Technical Program Committee solicits symposium contributions, including data and analysis that advance the state-of-the-art knowledge, enhance or review the general knowledge, or discuss new topics related to on-chip ESD design, system ESD design, and EOS/ESD issues in manufacturing. The Technical Program Committee is inviting papers related, but not limited, to the following tracks:

- Advanced CMOS EOS/ESD and Latch-up
- ESD protection in Bipolar, RF, High-voltage, and BCD technologies
- ESD modeling, simulation and design automation
- EOS/ESD Failure analysis and case studies
- ESD and Latch-up testing
- System ESD design and troubleshooting issues
- ESD manufacturing control issues and target discussion
- Device, circuit and product reliability

**Event Highlights:** Awards are presented annually for the Symposium Outstanding Paper and Best Student Paper Award (selected by the Technical Program Committee). The Outstanding Paper is considered for presentation at the Annual EOS/ESD Symposium.

**Submission Guidelines**
Authors must submit a maximum 50-word abstract and maximum 4-page summary of their work. The summary must clearly state the purpose, results (e.g., data, diagrams, photographs, etc.), and conclusions of the work. Summaries must also include references to prior publications and state how the work enhances existing knowledge. Authors suggest the technical area related to their submission. Abstract submissions can be made electronically at: [https://softconf.com/n/eos-esd2024](https://softconf.com/n/eos-esd2024)